

MC74AC245, MC74ACT245

Octal Bidirectional Transceiver with 3-State Inputs/Outputs

The MC74AC245/74ACT245 contains eight non-inverting bidirectional buffers with 3-state outputs and is intended for bus-oriented applications. Current sinking capability is 24 mA at both the A and B ports. The Transmit/Receive (T/R) input determines the direction of data flow through the bidirectional transceiver. Transmit (active-HIGH) enables data from A ports to B ports; Receive (active-LOW) enables data from B ports to A ports. The Output Enable input, when HIGH, disables both A and B ports by placing them in a High Z condition.

Features

- Noninverting Buffers
- Bidirectional Data Path
- A and B Outputs Source/Sink 24 mA
- 'ACT245 has TTL Compatible Inputs
- Pb-Free Packages are Available

PIN ASSIGNMENT

PIN	FUNCTION
OE	Output Enable Input
T/R	Transmit/Receive Input
A ₀ -A ₇	Side A 3-State Inputs or 3-State Outputs
B ₀ -B ₇	Side B 3-State Inputs or 3-State Outputs

TRUTH TABLES

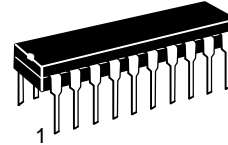
Inputs		Outputs
OE	T/R	
L	L	Bus B Data to Bus A
L	H	Bus A Data to Bus B
H	X	High Z State

H = HIGH Voltage Level
L = LOW Voltage Level
X = Immaterial

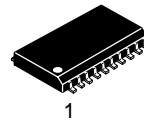


ON Semiconductor®

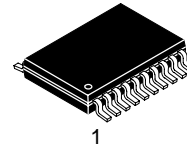
<http://onsemi.com>



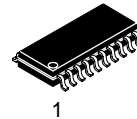
PDIP-20
N SUFFIX
CASE 738



SOIC-20W
DW SUFFIX
CASE 751D



TSSOP-20
DT SUFFIX
CASE 948E



SOEIAJ-20
M SUFFIX
CASE 967

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 6 of this data sheet.

DEVICE MARKING INFORMATION

See general marking information in the device marking section on page 7 of this data sheet.

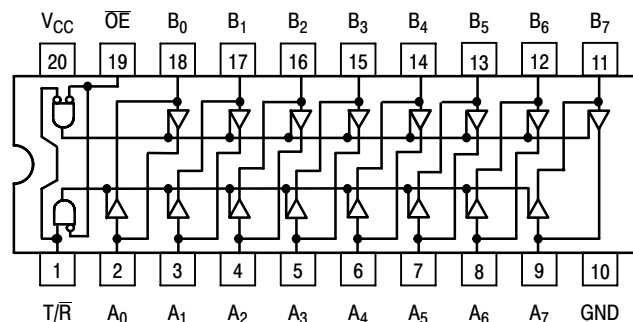


Figure 1.

MC74AC245, MC74ACT245

MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
V _{CC}	DC Supply Voltage (Referenced to GND)	-0.5 to +7.0	V
V _{IN}	DC Input Voltage (Referenced to GND)	-0.5 to V _{CC} +0.5	V
V _{OUT}	DC Output Voltage (Referenced to GND)	-0.5 to V _{CC} +0.5	V
I _{IN}	DC Input Current, per Pin	±20	mA
I _{OUT}	DC Output Sink/Source Current, per Pin	±50	mA
I _{CC}	DC V _{CC} or GND Current per Output Pin	±50	mA
T _{stg}	Storage Temperature	-65 to +150	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Typ	Max	Unit	
V _{CC}	Supply Voltage	'AC	2.0	5.0	6.0	V
		'ACT	4.5	5.0	5.5	
V _{IN} , V _{OUT}	DC Input Voltage, Output Voltage (Ref. to GND)	0	-	V _{CC}	V	
t _r , t _f	Input Rise and Fall Time (Note 1) 'AC Devices except Schmitt Inputs	V _{CC} @ 3.0 V	-	150	-	ns/V
		V _{CC} @ 4.5 V	-	40	-	
		V _{CC} @ 5.5 V	-	25	-	
t _r , t _f	Input Rise and Fall Time (Note 2) 'ACT Devices except Schmitt Inputs	V _{CC} @ 4.5 V	-	10	-	ns/V
		V _{CC} @ 5.5 V	-	8.0	-	
T _J	Junction Temperature (PDIP)	-	-	140	°C	
T _A	Operating Ambient Temperature Range	-40	25	85	°C	
I _{OH}	Output Current – High	-	-	-24	mA	
I _{OL}	Output Current – Low	-	-	24	mA	

1. V_{IN} from 30% to 70% V_{CC}; see individual Data Sheets for devices that differ from the typical input rise and fall times.
2. V_{IN} from 0.8 V to 2.0 V; see individual Data Sheets for devices that differ from the typical input rise and fall times.

MC74AC245, MC74ACT245

DC CHARACTERISTICS

Symbol	Parameter	V _{CC} (V)	74AC		74AC		Unit	Conditions
			T _A = +25°C		T _A = -40°C to +85°C			
			Typ	Guaranteed Limits				
V _{IH}	Minimum High Level Input Voltage	3.0	1.5	2.1	2.1	V	V _{OUT} = 0.1 V or V _{CC} - 0.1 V	
		4.5	2.25	3.15	3.15			
		5.5	2.75	3.85	3.85			
V _{IL}	Maximum Low Level Input Voltage	3.0	1.5	0.9	0.9	V	V _{OUT} = 0.1 V or V _{CC} - 0.1 V	
		4.5	2.25	1.35	1.35			
		5.5	2.75	1.65	1.65			
V _{OH}	Minimum High Level Output Voltage	3.0	2.99	2.9	2.9	V	I _{OUT} = -50 μA	
		4.5	4.49	4.4	4.4			
		5.5	5.49	5.4	5.4			
			3.0	-	2.56	2.46	V	*V _{IN} = V _{IL} or V _{IH} -12 mA I _{OH} -24 mA -24 mA
			4.5	-	3.86	3.76		
			5.5	-	4.86	4.76		
V _{OL}	Maximum Low Level Output Voltage	3.0	0.002	0.1	0.1	V	I _{OUT} = 50 μA	
		4.5	0.001	0.1	0.1			
		5.5	0.001	0.1	0.1			
			3.0	-	0.36	0.44	V	*V _{IN} = V _{IL} or V _{IH} 12 mA I _{OL} 24 mA 24 mA
			4.5	-	0.36	0.44		
			5.5	-	0.36	0.44		
I _{IN}	Maximum Input Leakage Current	5.5	-	±0.1	±1.0	μA	V _I = V _{CC} , GND	
I _{OZT}	Maximum 3-State Current	5.5	-	±0.6	±6.0	μA	V _I (OE) = V _{IL} , V _{IH} V _I = V _{CC} , GND V _O = V _{CC} , GND	
I _{OLD}	†Minimum Dynamic Output Current	5.5	-	-	75	mA	V _{OLD} = 1.65 V Max	
I _{OHD}		5.5	-	-	-75	mA	V _{OHD} = 3.85 V Min	
I _{CC}	Maximum Quiescent Supply Current	5.5	-	8.0	80.0	μA	V _{IN} = V _{CC} or GND	

*All outputs loaded; thresholds on input associated with output under test.

†Maximum test duration 2.0 ms, one output loaded at a time.

NOTE: I_{IN} and I_{CC} @ 3.0 V are guaranteed to be less than or equal to the respective limit @ 5.5 V V_{CC}.

MC74AC245, MC74ACT245

AC CHARACTERISTICS (For Figures and Waveforms – See AND8277/D at www.onsemi.com)

Symbol	Parameter	V _{CC} * (V)	74AC			74AC		Unit	Fig. No.
			T _A = +25°C C _L = 50 pF			T _A = -40°C to +85°C C _L = 50 pF			
			Min	Typ	Max	Min	Max		
t _{PLH}	Propagation Delay A _n to B _n or B _n to A _n	3.3 5.0	1.5 1.5	5.0 3.5	8.5 6.5	1.0 1.0	9.0 7.0	ns	3-5
t _{PHL}	Propagation Delay A _n to B _n or B _n to A _n	3.3 5.0	1.5 1.5	5.0 3.5	8.5 6.0	1.0 1.0	9.0 7.0	ns	3-5
t _{PZH}	Output Enable Time	3.3 5.0	2.5 1.5	7.0 5.0	11.5 8.5	2.0 1.0	12.5 9.0	ns	3-7
t _{PZL}	Output Enable Time	3.3 5.0	2.5 1.5	7.5 5.5	12.0 9.0	2.0 1.0	13.5 9.5	ns	3-8
t _{PHZ}	Output Disable Time	3.3 5.0	2.0 1.5	6.5 5.5	12.0 9.0	1.0 1.0	12.5 10.0	ns	3-7
t _{PLZ}	Output Disable Time	3.3 5.0	2.0 1.5	7.0 5.5	11.5 9.0	1.5 1.0	13.0 10.0	ns	3-8

*Voltage Range 3.3 V is 3.3 V ±0.3 V.
Voltage Range 5.0 V is 5.0 V ±0.5 V.

DC CHARACTERISTICS

Symbol	Parameter	V _{CC} (V)	74ACT		74ACT		Unit	Conditions
			T _A = +25°C		T _A = -40°C to +85°C			
			Typ	Guaranteed Limits				
V _{IH}	Minimum High Level Input Voltage	4.5	1.5	2.0	2.0	V	V _{OUT} = 0.1 V or V _{CC} - 0.1 V	
		5.5	1.5	2.0	2.0			
V _{IL}	Maximum Low Level Input Voltage	4.5	1.5	0.8	0.8	V	V _{OUT} = 0.1 V or V _{CC} - 0.1 V	
		5.5	1.5	0.8	0.8			
V _{OH}	Minimum High Level Output Voltage	4.5	4.49	4.4	4.4	V	I _{OUT} = -50 μA	
		5.5	5.49	5.4	5.4			
		4.5	-	3.86	3.76	V	*V _{IN} = V _{IL} or V _{IH} I _{OH} = -24 mA	
		5.5	-	4.86	4.76			
V _{OL}	Maximum Low Level Output Voltage	4.5	0.001	0.1	0.1	V	I _{OUT} = 50 μA	
		5.5	0.001	0.1	0.1			
		4.5	-	0.36	0.44	V	*V _{IN} = V _{IL} or V _{IH} I _{OL} = 24 mA	
		5.5	-	0.36	0.44			
I _{IN}	Maximum Input Leakage Current	5.5	-	±0.1	±1.0	μA	V _I = V _{CC} , GND	
ΔI _{CC} T	Additional Max. I _{CC} /Input	5.5	0.6	-	1.5	mA	V _I = V _{CC} - 2.1 V	
I _{OZT}	Maximum 3-State Current	5.5	-	±0.6	±6.0	μA	V _I (OE) = V _{IL} , V _{IH} V _I = V _{CC} , GND V _O = V _{CC} , GND	
I _{OLD}	†Minimum Dynamic Output Current	5.5	-	-	75	mA	V _{OLD} = 1.65 V Max	
I _{OHD}		5.5	-	-	-75	mA	V _{OHD} = 3.85 V Min	
I _{CC}	Maximum Quiescent Supply Current	5.5	-	8.0	80.0	μA	V _{IN} = V _{CC} or GND	

*All outputs loaded; thresholds on input associated with output under test.

†Maximum test duration 2.0 ms, one output loaded at a time.

MC74AC245, MC74ACT245

AC CHARACTERISTICS (For Figures and Waveforms – See AND8277/D at www.onsemi.com)

Symbol	Parameter	V _{CC} * (V)	74ACT			74ACT		Unit	Fig. No.
			T _A = +25°C C _L = 50 pF			T _A = -40°C to +85°C C _L = 50 pF			
			Min	Typ	Max	Min	Max		
t _{PLH}	Propagation Delay, A _n to B _n or B _n to A _n	5.0	1.5	4.0	7.5	1.5	8.0	ns	3-5
t _{PHL}	Propagation Delay, A _n to B _n or B _n to A _n	5.0	1.5	4.0	8.0	1.0	9.0	ns	3-5
t _{PZH}	Output Enable Time	5.0	1.5	5.0	10	1.5	11.0	ns	3-7
t _{PZL}	Output Enable Time	5.0	1.5	5.5	10	1.5	12.0	ns	3-8
t _{PHZ}	Output Disable Time	5.0	1.5	5.5	10	1.0	11.0	ns	3-7
t _{PLZ}	Output Disable Time	5.0	2.0	5.0	10	1.5	11.0	ns	3-8

*Voltage Range 5.0 V is 5.0 V ±0.5 V.

CAPACITANCE

Symbol	Parameter	Value Typ	Unit	Test Conditions
C _{IN}	Input Capacitance	4.5	pF	V _{CC} = 5.0 V
C _{I/O}	Input/Output Capacitance	15	pF	V _{CC} = 5.0 V
C _{PD}	Power Dissipation Capacitance	45	pF	V _{CC} = 5.0 V

MC74AC245, MC74ACT245

ORDERING INFORMATION

Device	Package	Shipping†
MC74AC245N	PDIP-20	18 Units / Rail
MC74AC245NG	PDIP-20 (Pb-Free)	
MC74ACT245N	PDIP-20	
MC74ACT245NG	PDIP-20 (Pb-Free)	
MC74AC245DW	SOIC-20	38 Units / Rail
MC74AC245DWG	SOIC-20 (Pb-Free)	
MC74AC245DWR2	SOIC-20	1000 / Tape & Reel
MC74AC245DWR2G	SOIC-20 (Pb-Free)	
MC74ACT245DW	SOIC-20	38 Units / Rail
MC74ACT245DWG	SOIC-20 (Pb-Free)	
MC74ACT245DWR2	SOIC-20	1000 / Tape & Reel
MC74ACT245DWR2G	SOIC-20 (Pb-Free)	
MC74AC245DT	TSSOP-20*	75 Units / Rail
MC74AC245DTG	TSSOP-20*	
MC74AC245DTR2	TSSOP-20*	2500 / Tape & Reel
MC74AC245DTR2G	TSSOP-20*	
MC74ACT245DT	TSSOP-20*	75 Units / Rail
MC74ACT245DTG	TSSOP-20*	
MC74ACT245DTR2	TSSOP-20*	2500 / Tape & Reel
MC74ACT245DTR2G	TSSOP-20*	
MC74AC245M	SOEIAJ-20	40 Units / Rail
MC74AC245MG	SOEIAJ-20 (Pb-Free)	
MC74AC245MEL	SOEIAJ-20	2000 / Tape & Reel
MC74AC245MELG	SOEIAJ-20 (Pb-Free)	
MC74ACT245M	SOEIAJ-20	40 Units / Rail
MC74ACT245MG	SOEIAJ-20 (Pb-Free)	
MC74ACT245MEL	SOEIAJ-20	2000 / Tape & Reel
MC74ACT245MELG	SOEIAJ-20 (Pb-Free)	

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

*These packages are inherently Pb-Free.

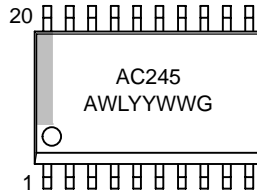
MC74AC245, MC74ACT245

MARKING DIAGRAMS

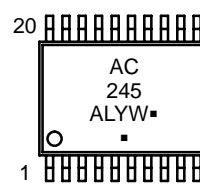
PDIP-20



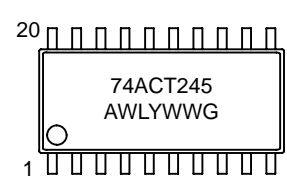
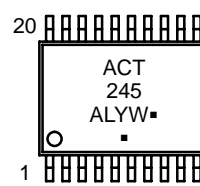
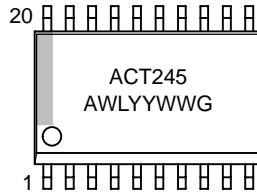
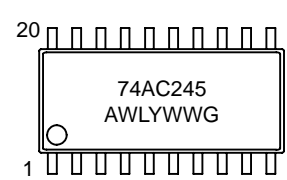
SOIC-20W



TSSOP-20



SOEIAJ-20



A = Assembly Location
 WL, L = Wafer Lot
 YY, Y = Year
 WW, W = Work Week
 G or ▪ = Pb-Free Package
 (Note: Microdot may be in either location)

MC74AC245, MC74ACT245

PACKAGE DIMENSIONS

PDIP-20
N SUFFIX
PLASTIC DIP PACKAGE
CASE 738-03
ISSUE E



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. DIMENSION L TO CENTER OF LEAD WHEN FORMED PARALLEL.
 4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	1.010	1.070	25.66	27.17
B	0.240	0.260	6.10	6.60
C	0.150	0.180	3.81	4.57
D	0.015	0.022	0.39	0.55
E	0.050 BSC		1.27 BSC	
F	0.050	0.070	1.27	1.77
G	0.100 BSC		2.54 BSC	
J	0.008	0.015	0.21	0.38
K	0.110	0.140	2.80	3.55
L	0.300 BSC		7.62 BSC	
M	0°	15°	0°	15°
N	0.020	0.040	0.51	1.01

SOIC-20W
DW SUFFIX
CASE 751D-05
ISSUE G



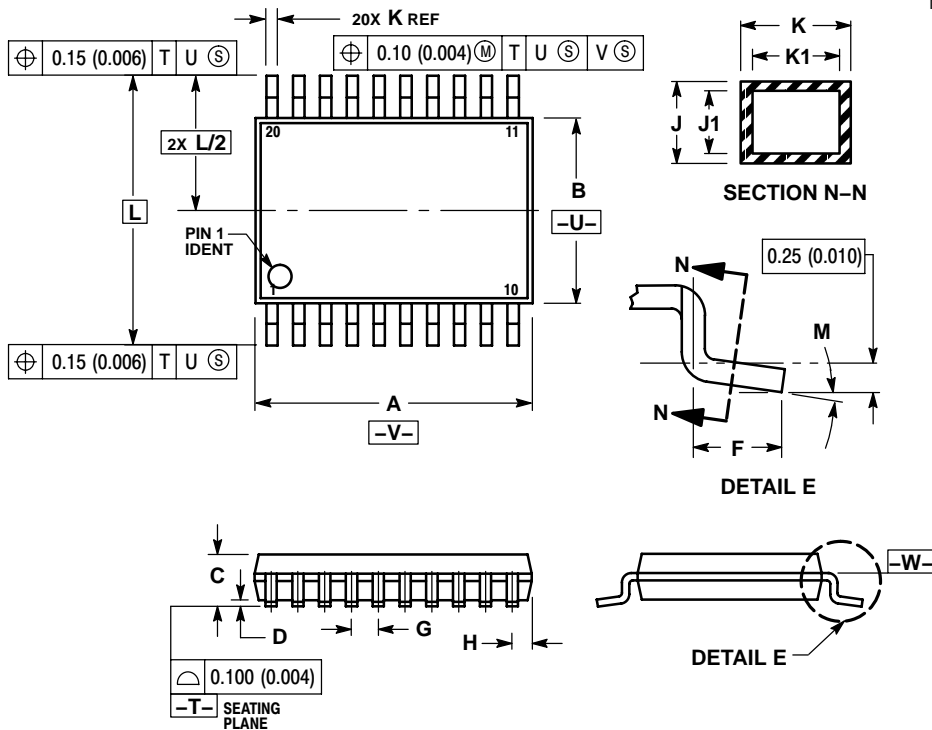
- NOTES:
1. DIMENSIONS ARE IN MILLIMETERS.
 2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994.
 3. DIMENSIONS D AND E DO NOT INCLUDE MOLD PROTRUSION.
 4. MAXIMUM MOLD PROTRUSION 0.15 PER SIDE.
 5. DIMENSION B DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.13 TOTAL IN EXCESS OF B DIMENSION AT MAXIMUM MATERIAL CONDITION.

DIM	MILLIMETERS	
	MIN	MAX
A	2.35	2.65
A1	0.10	0.25
B	0.35	0.49
C	0.23	0.32
D	12.65	12.95
E	7.40	7.60
e	1.27 BSC	
H	10.05	10.55
h	0.25	0.75
L	0.50	0.90
theta	0°	7°

MC74AC245, MC74ACT245

PACKAGE DIMENSIONS

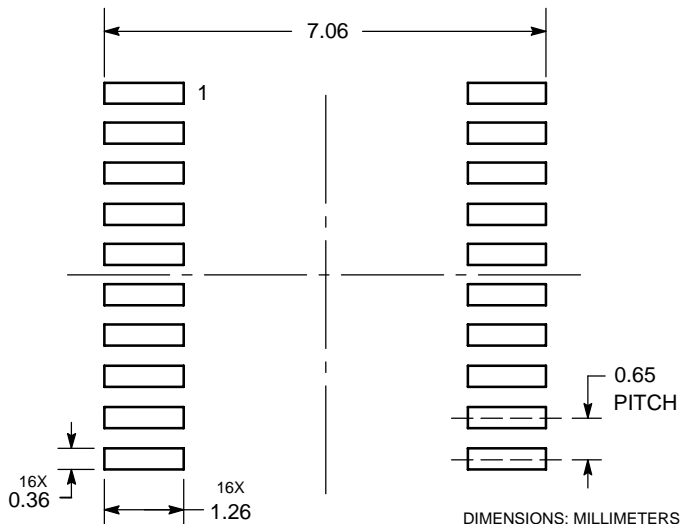
TSSOP-20
DT SUFFIX
CASE 948E-02
ISSUE C



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETER.
 3. DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
 4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
 5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
 6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
 7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	6.40	6.60	0.252	0.260
B	4.30	4.50	0.169	0.177
C	---	1.20	---	0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65 BSC		0.026 BSC	
H	0.27	0.37	0.011	0.015
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40 BSC		0.252 BSC	
M	0°	8°	0°	8°

SOLDERING FOOTPRINT*

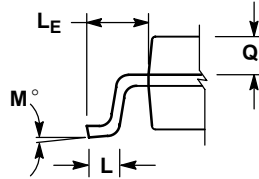


*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

MC74AC245, MC74ACT245

PACKAGE DIMENSIONS

SOEIAJ-20
M SUFFIX
CASE 967-01
ISSUE A



DETAIL P



NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS AND ARE MEASURED AT THE PARTING LINE. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
5. THE LEAD WIDTH DIMENSION (b) DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSIONS AND ADJACENT LEAD TO BE 0.46 (0.018).

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	---	2.05	---	0.081
A ₁	0.05	0.20	0.002	0.008
b	0.35	0.50	0.014	0.020
c	0.15	0.25	0.006	0.010
D	12.35	12.80	0.486	0.504
E	5.10	5.45	0.201	0.215
e	1.27 BSC		0.050 BSC	
HE	7.40	8.20	0.291	0.323
L	0.50	0.85	0.020	0.033
LE	1.10	1.50	0.043	0.059
M	0° - 10°		0° - 10°	
Q ₁	0.70	0.90	0.028	0.035
Z	---	0.81	---	0.032

ON Semiconductor and are registered trademarks of Semiconductor Components Industries, LLC (SCILLC). SCILLC reserves the right to make changes without further notice to any products herein. SCILLC makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does SCILLC assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. "Typical" parameters which may be provided in SCILLC data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. SCILLC does not convey any license under its patent rights nor the rights of others. SCILLC products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the SCILLC product could create a situation where personal injury or death may occur. Should Buyer purchase or use SCILLC products for any such unintended or unauthorized application, Buyer shall indemnify and hold SCILLC and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that SCILLC was negligent regarding the design or manufacture of the part. SCILLC is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:
Literature Distribution Center for ON Semiconductor
P.O. Box 5163, Denver, Colorado 80217 USA
Phone: 303-675-2175 or 800-344-3860 Toll Free USA/Canada
Fax: 303-675-2176 or 800-344-3867 Toll Free USA/Canada
Email: orderlit@onsemi.com

N. American Technical Support: 800-282-9855 Toll Free USA/Canada
Europe, Middle East and Africa Technical Support:
Phone: 421 33 790 2910
Japan Customer Focus Center
Phone: 81-3-5773-3850

ON Semiconductor Website: www.onsemi.com
Order Literature: <http://www.onsemi.com/orderlit>

For additional information, please contact your local Sales Representative

MC74AC245/D